<u>Amendments to the Claims:</u>

Claims 4, 10, and 20 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application. Please cancel claims 1-3, 5-9, 11-19, and 21-30 without prejudice to the filing of one or more divisional applications including same.

<u>Listing of Claims:</u>

Claims 1-3 (canceled)

4.   (currently twice amended) [A semiconductor device according to claim 4, wherein the openings comprise] <u>A semiconductor device having an improved bond pad, the semiconductor device comprising:</u>

    a.   <u>a bond pad electrically connected to an active circuit in the semiconductor device;</u>

    b.   <u>a substantially flat bonding surface on the bond pad; and</u>

    c.   <u>a plurality of openings extending partially into the bonding surface and forming</u> a pattern of radiating channels disposed about a center of the bonding surface.

Claims 5-9 (canceled)

10.   (currently amended) [A semiconductor device according to claim 8,] <u>A</u> <u>semiconductor device, which comprises:</u>

    a.   <u>an active circuit in the semiconductor device;</u>

    b.   <u>a wiring pattern overlying and in electrical contact with the active circuit;</u>

    c.   <u>bond pads formed as select areas on the wiring pattern; and</u>

    d.   <u>a plurality of openings extending partially into a substantially flat bonding surface</u> <u>of the bond pads,</u> wherein the openings comprise a pattern of radiating channels disposed about a center of the bonding surface.

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Claims 11-19 (canceled)

20.   (currently amended) [An improved bond pad according to claim 18] An improved bond pad comprising:

a metal layer having a substantially planar surface, said metal layer electrically connected to an active circuit of a semiconductor device and having a plurality of openings extending partially into said metal layer, wherein the openings comprise a pattern of radiating channels disposed about a center of the bond pad.

Claims 21-30 (canceled)